

# High Power Density and Power Added Efficiency of $\text{Al}_{0.5}\text{In}_{0.5}\text{P}/\text{InGaAs}$ Doped-channel HFETs

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## Abstract

DX-center related problems limit  $x$  to  $\leq 0.22$  for  $\text{Al}_x\text{Ga}_x\text{As}$  Schottky layer system. In this study,  $\text{Al}_{0.5}\text{In}_{0.5}\text{P}/\text{In}_{0.15}\text{Ga}_{0.85}\text{As}$  doped-channel HFETs (DCFETs) demonstrate a high breakdown voltage, a high power density, and a high linearity for microwave power device applications due to the improvement of a larger  $\Delta E_c$  (0.45eV) and a wide bandgap AlInP Schottky layer. The device, biased at  $V_{ds}=3.0\text{V}$  and operated at 2.4 GHz, provided an output power density of 209 mW/mm, a power-added efficiency of 59 % and a linear power gain of 17 dB. Two-tone measurement reveals that the 3rd-order inter-modulation at an input power of 0 dBm is -29 dBc and the output intercept point ( $\text{OIP}_3$ ) is 30.4 dBm for devices with a 1mm-wide gate.